Advansic   Pulse Heat Tools

Features

● The heat tool for semiconductor bonding process.

● Excellent thermal response and uniformity by generating the heat from the SiC ceramic itself.

● The heat reaches at the max rate of 200C/sec.

● Enable to achieve pulse heating with the minimum of 500W electric power.

   (Only for the operation of 12 x 12mm heat tool without attachment)

● The available sizes are: 12 x 12 mm, 22 x 22 mm, 35 x 35 mm

Production code	Size	Recommended object size	max. temperature	max. heat rate	Cooling time	Temperature uniformity
PHT-12	12×12mm	～7mm	450℃	200℃/sec	2.4sec*1	±6℃ (450℃, within 5mm□)
PHT-22	22×22mm	～15mm	450℃	200℃/sec	4.7sec*1	±5℃ (450℃, within 5mm□)
PHT-35	35×35mm	15～25mm	450℃	150℃/sec	7.6sec*1	±9℃ (450℃, within 5mm□)

Without attachment (Heat tool only), Apply only internal cooling line 0.5MPa – 1 source.

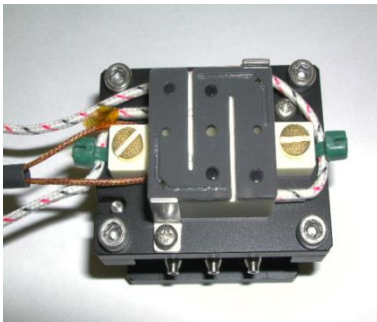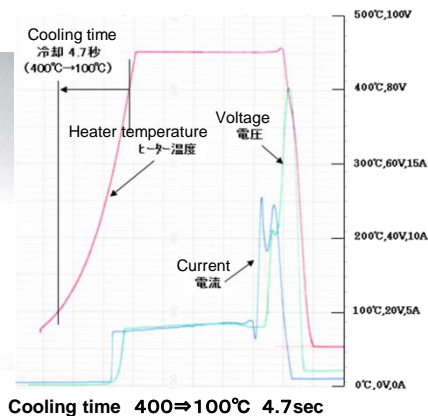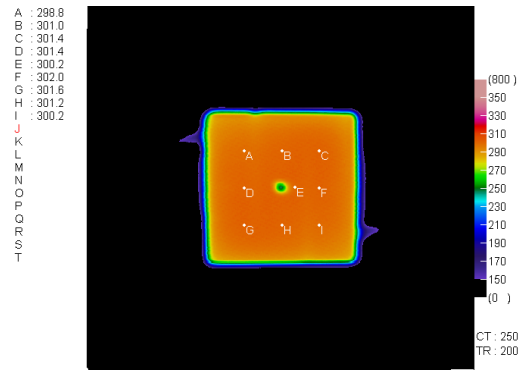## 22 x 22mm Pulse Heat Tool PHT-22

Fig.1   Appearance

Cooling time   400⇒100℃   4.7sec

Fig.2   Time chart of heater performance (Heat tool only)

ΔT＝3.2℃ （±1.6℃） ；within 12mm

Fig.3 Temperature uniformity on the attachment (measured by infrared thermometer)